



# HJ1538

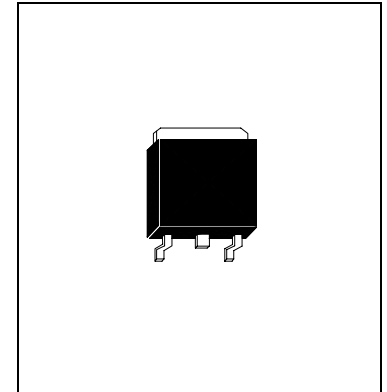
PNP EPITAXIAL PLANAR TRANSISTOR

## Description

High-definition CRT display video output, wide-band amp.

## Features

- High  $f_T$ :  $f_T=400\text{MHz}$
- High breakdown voltage:  $V_{CEO}=-120\text{Vmin}$
- Small reverse transfer capacitance and excellent HF response



## Absolute Maximum Ratings (Ta=25°C)

- Maximum Temperatures  
Storage Temperature ..... -55 ~ +150 °C  
Junction Temperature ..... +150 °C
- Maximum Power Dissipation  
Total Power Dissipation (Tc=25°C) ..... 1.3 W
- Maximum Voltages and Currents  
BVCBO Collector to Base Voltage ..... -120 V  
BVCEO Collector to Emitter Voltage ..... -120 V  
BVEBO Emitter to Base Voltage ..... -3 V  
IC Collector Current ..... -100 mA  
IC Peak Collector Current ..... -100 mA

## Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	-120	-	-	V	IC=-10uA, IE=0
BVCEO	-120	-	-	V	IC=-1mA, IB=0
BVEBO	-3	-	-	V	IE=-100uA, IC=0
ICBO	-	-	-100	nA	VCB=-80V
IEBO	-	-	-100	nA	VEB=-2V
*VCE(sat)	-	-	-1	V	IC=-30mA, IB=-3mA
*VBE(sat)	-	-	-1	V	IC=-30mA, IB=-3mA
*hFE1	60	160	320		VCE=-10V, IC=-10mA
*hFE2	40	-	-		VCE=-10V, IC=-100mA
fT	400	-	-	MHz	VCE=-10V, IC=-50mA
Cob	2.8	-	-	pF	VCB=-30V, f=1MHz

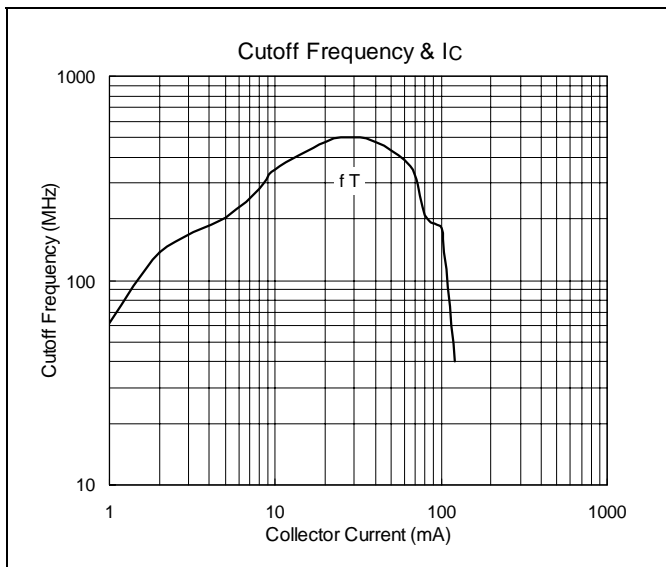
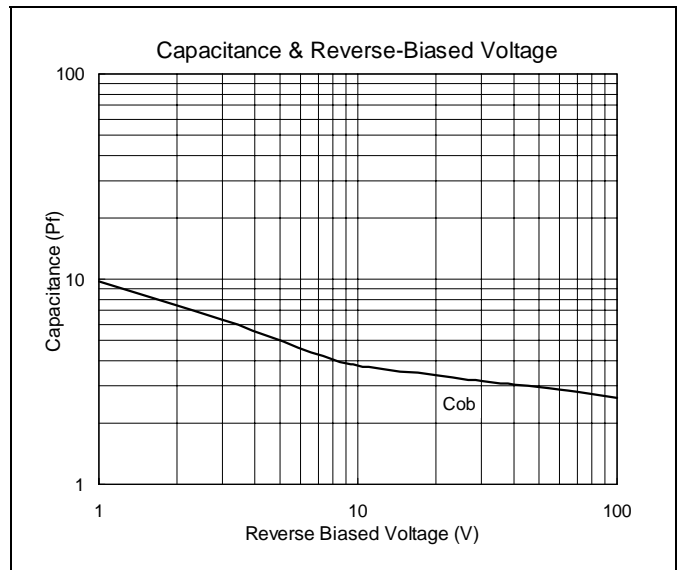
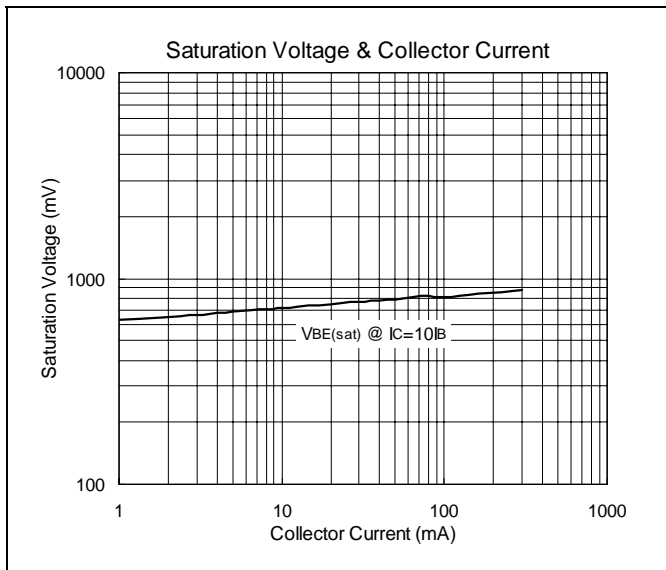
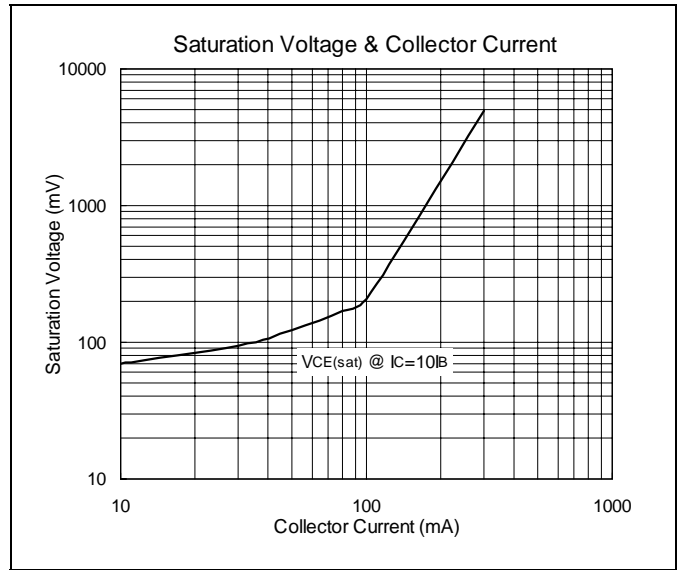
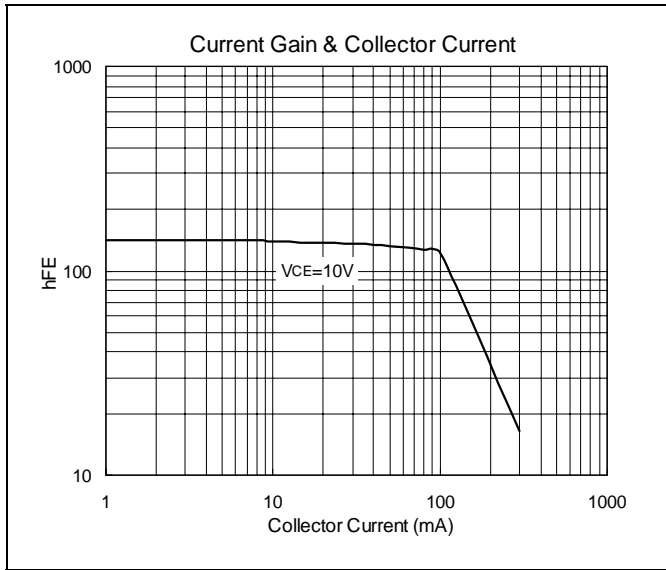
\*Pulse Test : Pulse Width ≤380us, Duty Cycle≤2%

## Classification Of hFE1

Rank	D	E	F
Range	60-120	100-200	160-320

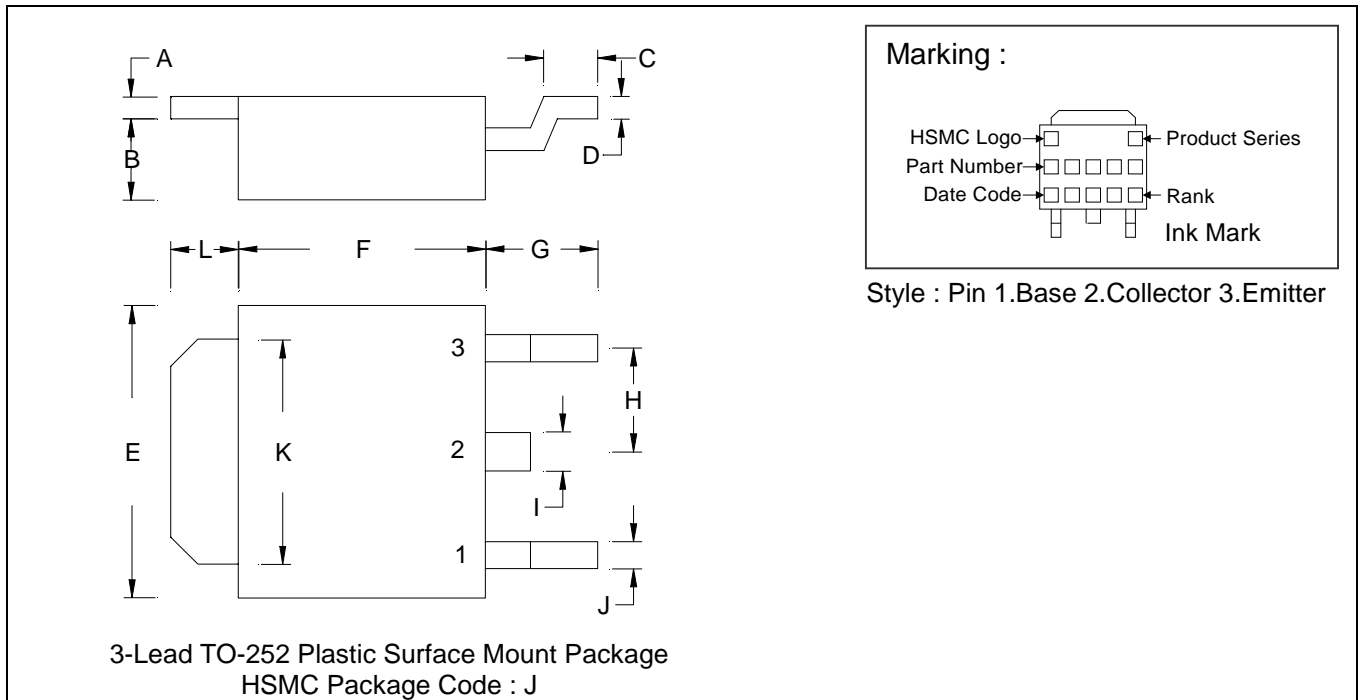


### Characteristics Curve





### TO-252 Dimension



\*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.0177	0.0217	0.45	0.55	G	0.0866	0.1102	2.20	2.80
B	0.0650	0.0768	1.65	1.95	H	-	*0.0906	-	*2.30
C	0.0354	0.0591	0.90	1.50	I	-	0.0354	-	0.90
D	0.0177	0.0236	0.45	0.60	J	-	0.0315	-	0.80
E	0.2520	0.2677	6.40	6.80	K	0.2047	0.2165	5.20	5.50
F	0.2125	0.2283	5.40	5.80	L	0.0551	0.0630	1.40	1.60

Notes : 1.Dimension and tolerance based on our Spec. dated May. 05,1996.  
 2.Controlling dimension : millimeters.  
 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.  
 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

**Material :**

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

**Important Notice:**

- All rights are reserved. Reproduction in whole or in part is prohibited without the prior written approval of HSMC.
- HSMC reserves the right to make changes to its products without notice.
- **HSMC semiconductor products are not warranted to be suitable for use in Life-Support Applications, or systems.**
- HSMC assumes no liability for any consequence of customer product design, infringement of patents, or application assistance.

**Head Office And Factory :**

- **Head Office** (Hi-Sincerity Microelectronics Corp.) : 10F.,No. 61, Sec. 2, Chung-Shan N. Rd. Taipei Taiwan R.O.C.  
Tel : 886-2-25212056 Fax : 886-2-25632712, 25368454
- **Factory 1** : No. 38, Kuang Fu S. Rd., Fu-Kou Hsin-Chu Industrial Park Hsin-Chu Taiwan. R.O.C  
Tel : 886-3-5983621~5 Fax : 886-3-5982931
- **Factory 2** : No. 17-1, Ta-Tung Rd., Fu-Kou Hsin-Chu Industrial Park Hsin-Chu Taiwan. R.O.C  
Tel : 886-3-5977061 Fax : 886-3-5979220